

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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KAZUOMI SUMI	11/05/2021
SHOGO OCHIAI	11/05/2021
KAZUNOBU HARA	11/05/2021
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17612722
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ATTORNEY DOCKET NUMBER:	YUCH1PUS01
NAME OF SUBMITTER:	PAUL R. STEFFES
SIGNATURE:	/Paul R. Steffes/
DATE SIGNED:	11/19/2021
Total Attachments: 2	
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source=ASSIGNMENT_executed_and_appl_data_added#page2.tif	

Renner Otto Docket No. YUCH1PUS01

PATENT (OUS)

ASSIGNMENT OF APPLICATION FOR PATENT
(US RIGHTS ONLY)

Whereas,

Name of Inventor(s)	Address
Kazuomi SUMI	c/o KAI R&D CENTER CO., LTD. 1110 Oyana, Seki-shi, Gifu 5013992, JAPAN
Shogo OCHIAI	c/o KAI R&D CENTER CO., LTD. 1110 Oyana, Seki-shi, Gifu 5013992, JAPAN
Kazunobu HARA	c/o KAI R&D CENTER CO., LTD. 1110 Oyana, Seki-shi, Gifu 5013992, JAPAN

(hereinafter referred to as ASSIGNOR), have invented a certain invention entitled:

TITLE: A Package Open Knife and a Package Open Knives Pack

for which application for Letters Patent of the United States has been filed under:

Application No. (<i>Express Mail Label No.</i>)	17/612,722
Filing Date (<i>Deposit Date</i>)	November 19, 2021

[Authorization is hereby given for any attorney of record in the subject patent application to insert above the application number and filing date information for this application when that information becomes available]

or, if no application is identified above, the application executed concurrently herewith.

For good and valuable consideration, receipt of which is hereby acknowledged, I have sold and assigned and hereby sell and assign to:

Assignee(s)	Address
KAI R&D CENTER CO., LTD.	1110 Oyana, Seki-shi, Gifu 5013992 JAPAN

[If more than one assignee is listed, each owns an undivided equal share in the application and underlying invention so far as concerns the United States unless otherwise indicated or agreed to by the assignees.]

and the successors and assigns thereof, the entire right, title and interest to said invention so far as concerns the United States and the Territories and Possessions thereof, including the right to claim priority, and said application and all Letters Patent of the United States to be obtained on said application, and any related applications including any nonprovisional application, continuation, division, renewal, substitute or reissue thereof, for the full term or terms for which the same may be

granted, and any U.S. nonprovisional, U.S. provisional and/or U.S. national phase patent application on which priority is claimed.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment and sale.

I further covenant that Assignee(s) will, upon request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent as may be known and accessible to me and will testify as to the same in any proceeding related thereto and will promptly execute and deliver to Assignee(s), or the legal representative thereof, any and all papers, instruments or affidavits required to apply for, obtain, maintain and enforce said application, said invention and said Letters Patent which may be necessary or desirable to carry out the purposes hereof.

I agree that this assignment shall be construed in accordance with the law of the appropriate jurisdiction within the United States, and without regard to its conflicts of laws provisions.

Name of Inventor(s)	Date	Signature
Kazuomi SUMI	Nov. 5, 2021	Kazuomi Sumi
Shogo OCHIAI	Nov. 5, 2021	Shogo Ochiai
Kazunobu HARA	Nov. 5, 2021	Kazunobu Hara